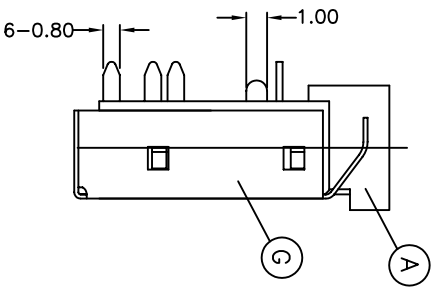
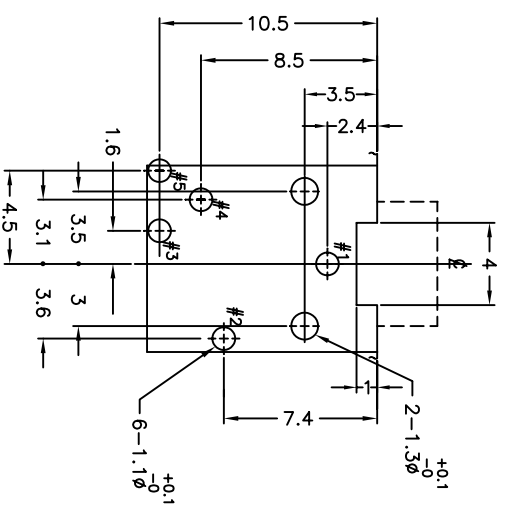
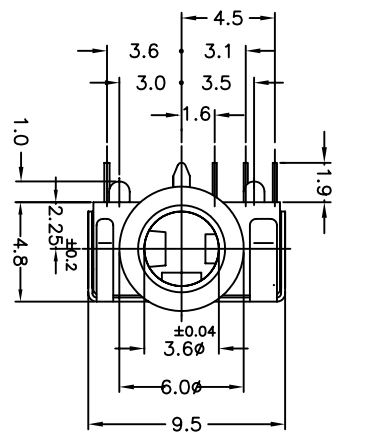
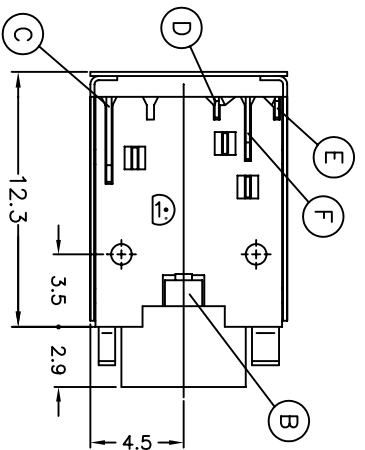
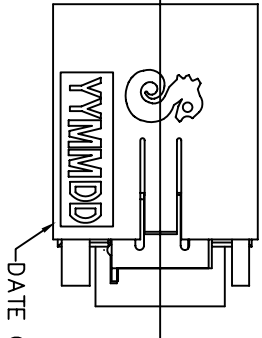
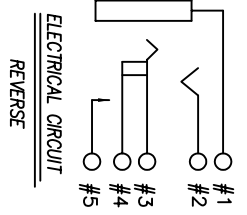


REV	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR RELEASE	EVEN	2006.9.1



RECOMMENDED PCB LAYOUT  
BOTTOM VIEW  
(TOLERANCE: ±0.05)



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
  - CONTACT RESISTANCE: 50mΩ MAX.
  - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
  - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
  - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
  - INSERTION FORCE: 0.4 - 3Kg.
  - WITHDRAWAL FORCE: 0.3 - 2Kg.
  - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
  - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
  - MARKING: MARK "S" ON TOP OF CONNECTOR.
  - PACKING: TAPE & REEL.
  - TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE"
  - GREEN PRODUCT IDENTIFICATION MARK IN JACK:
  - GREEN PRODUCT IDENTIFICATION LABEL IN PACKING:
  - SOLDER HEAT RESISTANCE: 270°C 10 SECS.

G	SHIELDING	1	PHOSPHOR BRONZE 0.2t	NICKEL PLATING
F	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	SILVER PLATING
E	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	SILVER PLATING
D	RING SPRING	1	PHOSPHOR BRONZE 0.2t	SILVER PLATING
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	SILVER PLATING
B	EARTH	1	COPPER ALLOY 0.3t	SILVER PLATING
A	BODY	1	HIGH TEMP-THERMOPLASTIC UL 94V-0	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
Singaton Enterprise Co., Ltd. 信音企業股份有限公司				
TITLE: 3.5Φ PHONE JACK				
DWG: 2006.01 PART NO: 251-S351-016				
CHKD: 2006.03 SCALE: 4/1 UNIT: mm				
APVD: 2006.05 SIZE: A3 SHEET: 1 OF 1 REV: A				
CUSTOMER COPY				